Compliant with IEC 62474/ D9.00

MICROCHIP Semiconductor Device Type:	(JEX) 048 TQFP 7x7x1.4 Matte Tin		Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3	
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	100.97	(mg) Total	Mold Compound	% ot Total Weight	57.27
Silica Fused	60676-86-0	Mold Compound	50.552	89.124	505.522		Silica Fused	60676-86-0	88.27	
Epoxy Resin	Trade Secret	Mold Compound	3.574	6.300	35,736		Epoxy Resin	Trade Secret	6.24	
Phenol Resin	Trade Secret	Mold Compound	2.972	5.240	29,723		Phenol Resin	Trade Secret	5.19	
Carbon Black	1333-86-4	Mold Compound	0.172	0.303	1,718		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	33.515	59.087	335,153		Garbon Black	Total	100.00	
Nickel	7440-02-0	Lead Frame	0.894	1.576	8.938	62.04	(mg) Total	Lead Frame	% of Total Weight	35.19
Silver	7440-22-4	Lead Frame	0.587	1.035	5.873	02.04	Copper	7440-50-8	95.24	33.13
Silicon	7440-21-3	Lead Frame	0.158	0.279	1.584		Nickel	7440-02-0	2.54	
Magnesium	7439-95-4	Lead Frame	0.035	0.062	352		Silver	7440-22-4	1.67	
Silver	7440-22-4	Die Attach	0.930	1.640	9,300		Silicon	7440-21-3	0.45	
Epoxy Resin	Trade secret	Die Attach	0.310	0.547	3,100		Magnesium	7439-95-4	0.10	
Silicon	7440-21-3	Chip (Die)	3.570	6.294	35,700		Magnosiani	Total	100.00	
Gold	7440-57-5	Wire Bond	0.230	0.405	2,300	2.19	(mg) Total	Die Attach	% of Total Weight	1.24
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	2.500	4.408	25,000	2.19	Silver	7440-22-4	75.00	1.24
IIII	7440-31-3	TOTALS:	100.000	176.300	1.000.000		Epoxy Resin	Trade secret	25.00	
	0.4700	g Total Mass	100.000	170.300	1,000,000		Epoxy Resili	Total	100.00	
ch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) witho	ut exemption (ze	ro)			5/863/EU (31	6.29	(mg) Total	Chip (Die)	% of Total Weight	3.57
mpliance with the above EU Directives has been verified via	a internal design	controls, supplier declarations, and /or analytical test data		·		6.29	(mg) Total Doped Silicon	7440-21-3 Total	% of Total Weight 100.00 100.00	3.57
pliance with the above EU Directives has been verified vis chemical substance is absent from the list above, the cher nnology Incorporated's knowledge and belief as of the dat nical substance, if any, is not below the threshold of regui ding compounds used by Microchip meet the UL94 VO flan	a internal design mical substance i e of this docume latory concern fo nmability standar	controls, supplier declarations, and /or analytical test data s NOT an intentional ingredient in the semiconductor devi- nt, there is no credible reason to believe that the unavoida r any regulatory scheme world-wide.	ce and, to the ble impurity (best of Micro	chip of the	0.41	Doped Silicon	7440-21-3	100.00	0.23
mpliance with the above EU Directives has been verified via chemical substance is absent from the list above, the cher chnology Incorporated's knowledge and belief as of the dat amical substance, if any, is not below the threshold of regu- lding compounds used by Microchip meet the UL94 V0 flan p://ul.com/global/eng/pages/offerings/industries/chemicals/ e protective "tubes" in which the specific product is shippe	a internal design mical substance i e of this docume latory concern fo nmability standar /plastics/	controls, supplier declarations, and for analytical test data s NOT an intentional ingredient in the semiconductor devi nt, there is no credible reason to believe that the unavoida r any regulatory scheme world-wide. 'd for plastics. You can access the UL iQTM family of datal	ce and, to the ble impurity o	best of Micro concentration in a test repor	chip of the t at		,	7440-21-3 Total	100.00	
rch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) witho mpliance with the above EU Directives has been verified via chemical substance is absent from the list above, the cherchnology incorporated's knowledge and belief as of the datemical substance, if any, is not below the threshold of regulding compounds used by Microchip meet the UL94 V0 flan p://ul.com/global/eng/pages/offerings/industries/chemicals/e protective "tubes" in which the specific product is shippe x and certain "reels" may be made from PVC plastic. crochip Technology Incorporated believes the information i vices in their original packing materials is true and correct transtee the completeness and accuracy of data in this form tetrial suppliers. Supplier information is provided only as estimal mponents. These estimates do not include trace levels of details.	a internal design mical substance i e of this docume latory concern for mability standar /plastics/ ed are made from in this form conce to the best of its i because it has b m disclosure as t ttes of the averag	controls, supplier declarations, and /or analytical test data s NOT an intentional ingredient in the semiconductor devint, there is no credible reason to believe that the unavoida r any regulatory scheme world-wide. 'd for plastics. You can access the UL iQTM family of datal polyvinyl chloride (PVC) plastic. "Window envelopes" use erning substances restricted by RoHS in Microchip Technoknowledge and belief, as of the date listed in this form. Microen compiled based on the ranges provided in Material Sarade secrets and some information may not have been proe weight of these parts and the average weight of anticipal	ce and, to the ble impurity of pases to obta d to hold the blogy Incorporate Technicate State St	best of Micro concentration in a test repor packing slip o crated's semicology incorpo- cets provided l contract asse it toxic metals	chip of the t at on the outer onductor orated cannot by raw mblers and		Doped Silicon (mg) Total	7440-21-3 Total Wire Bond	100.00 100.00 % of Total Weight	
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